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"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "[Embedded - Microcontrollers](#)"

Details

Product Status	Active
Core Processor	MIPS32® M4K™
Core Size	32-Bit Single-Core
Speed	40MHz
Connectivity	I ² C, IrDA, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, I ² S, POR, PWM, WDT
Number of I/O	21
Program Memory Size	256KB (256K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	64K x 8
Voltage - Supply (Vcc/Vdd)	2.3V ~ 3.6V
Data Converters	A/D 10x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	28-SSOP (0.209", 5.30mm Width)
Supplier Device Package	28-SSOP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic32mx170f256bt-i-ss

PIC32MX1XX/2XX 28/36/44-PIN FAMILY

TABLE 4: PIN NAMES FOR 28-PIN USB DEVICES

28-PIN SOIC, SPDIP, SSOP (TOP VIEW) ^(1,2,3)							
	1	28	1	28	1	28	
	SSOP		SOIC		SPDIP		
PIC32MX210F016B PIC32MX220F032B PIC32MX230F064B PIC32MX230F256B PIC32MX250F128B PIC32MX270F256B							
Pin #	Full Pin Name	Pin #	Full Pin Name	Pin #	Full Pin Name	Pin #	Full Pin Name
1	MCLR	15	V _{BUS}	1		15	
2	PGED3/VREF+/CVREF+/AN0/C3INC/RPA0/CTED1/PMD7/RA0	16	TDI/RPB7/CTED3/PMD5/INT0/RB7	2		16	
3	PGEC3/VREF-/CVREF-/AN1/RPA1/CTED2/PMD6/RA1	17	TCK/RPB8/SCL1/CTED10/PMD4/RB8	3		17	
4	PGED1/AN2/C1IND/C2INB/C3IND/RPB0/PMD0/RB0	18	TDO/RPB9/SDA1/CTED4/PMD3/RB9	4		18	
5	PGEC1/AN3/C1INC/C2INA/RPB1/CTED12/PMD1/RB1	19	V _{SS}	5		19	
6	AN4/C1INB/C2IND/RPB2/SDA2/CTED13/PMD2/RB2	20	V _{CAP}	6		20	
7	AN5/C1INA/C2INC/RTCC/RPB3/SCL2/PMWR/RB3	21	PGED2/RPB10/D+/CTED11/RB10	7		21	
8	V _{SS}	22	PGEC2/RPB11/D-/RB11	8		22	
9	OSC1/CLKI/RPA2/RA2	23	V _{USB3V3}	9		23	
10	OSC2/CLKO/RPA3/PMA0/RA3	24	AN11/RPB13/CTPLS/PMRD/RB13	10		24	
11	SOSCI/RPB4/RB4	25	CVREFOUT/AN10/C3INB/RPB14/V _{BUSON} /SCK1/CTED5/RB14	11		25	
12	SOSCO/RPA4/T1CK/CTED9/PMA1/RA4	26	AN9/C3INA/RPB15/SCK2/CTED6/PMCS1/RB15	12		26	
13	V _{DD}	27	AV _{SS}	13		27	
14	TMS/RPB5/USBID/RB5	28	AV _{DD}	14		28	

- Note**
- 1: The RPN pins can be used by remappable peripherals. See Table 1 for the available peripherals and **Section 11.3 “Peripheral Pin Select”** for restrictions.
 - 2: Every I/O port pin (RAX-RCx) can be used as a change notification pin (CNAX-CNCx). See **Section 11.0 “I/O Ports”** for more information.
 - 3: Shaded pins are 5V tolerant.

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Referenced Sources

This device data sheet is based on the following individual chapters of the “PIC32 Family Reference Manual”. These documents should be considered as the general reference for the operation of a particular module or device feature.

Note: To access the following documents, refer to the <i>Documentation > Reference Manuals</i> section of the Microchip PIC32 website: http://www.microchip.com/pic32

- **Section 1. “Introduction”** (DS60001127)
- **Section 2. “CPU”** (DS60001113)
- **Section 3. “Memory Organization”** (DS60001115)
- **Section 5. “Flash Program Memory”** (DS60001121)
- **Section 6. “Oscillator Configuration”** (DS60001112)
- **Section 7. “Resets”** (DS60001118)
- **Section 8. “Interrupt Controller”** (DS60001108)
- **Section 9. “Watchdog Timer and Power-up Timer”** (DS60001114)
- **Section 10. “Power-Saving Features”** (DS60001130)
- **Section 12. “I/O Ports”** (DS60001120)
- **Section 13. “Parallel Master Port (PMP)”** (DS60001128)
- **Section 14. “Timers”** (DS60001105)
- **Section 15. “Input Capture”** (DS60001122)
- **Section 16. “Output Compare”** (DS60001111)
- **Section 17. “10-bit Analog-to-Digital Converter (ADC)”** (DS60001104)
- **Section 19. “Comparator”** (DS60001110)
- **Section 20. “Comparator Voltage Reference (CVREF)”** (DS60001109)
- **Section 21. “Universal Asynchronous Receiver Transmitter (UART)”** (DS60001107)
- **Section 23. “Serial Peripheral Interface (SPI)”** (DS60001106)
- **Section 24. “Inter-Integrated Circuit (I²C)”** (DS60001116)
- **Section 27. “USB On-The-Go (OTG)”** (DS60001126)
- **Section 29. “Real-Time Clock and Calendar (RTCC)”** (DS60001125)
- **Section 31. “Direct Memory Access (DMA) Controller”** (DS60001117)
- **Section 32. “Configuration”** (DS60001124)
- **Section 33. “Programming and Diagnostics”** (DS60001129)
- **Section 37. “Charge Time Measurement Unit (CTMU)”** (DS60001167)

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TABLE 1-1: PINOUT I/O DESCRIPTIONS (CONTINUED)

Pin Name	Pin Number ⁽¹⁾				Pin Type	Buffer Type	Description
	28-pin QFN	28-pin SSOP/ SPDIP/ SOIC	36-pin VTLA	44-pin QFN/ TQFP/ VTLA			
OC1	PPS	PPS	PPS	PPS	O	—	Output Compare Output 1
OC2	PPS	PPS	PPS	PPS	O	—	Output Compare Output 2
OC3	PPS	PPS	PPS	PPS	O	—	Output Compare Output 3
OC4	PPS	PPS	PPS	PPS	O	—	Output Compare Output 4
OC5	PPS	PPS	PPS	PPS	O	—	Output Compare Output 5
OCFA	PPS	PPS	PPS	PPS	I	ST	Output Compare Fault A Input
OCFB	PPS	PPS	PPS	PPS	I	ST	Output Compare Fault B Input
INT0	13	16	17	43	I	ST	External Interrupt 0
INT1	PPS	PPS	PPS	PPS	I	ST	External Interrupt 1
INT2	PPS	PPS	PPS	PPS	I	ST	External Interrupt 2
INT3	PPS	PPS	PPS	PPS	I	ST	External Interrupt 3
INT4	PPS	PPS	PPS	PPS	I	ST	External Interrupt 4
RA0	27	2	33	19	I/O	ST	PORTA is a bidirectional I/O port
RA1	28	3	34	20	I/O	ST	
RA2	6	9	7	30	I/O	ST	
RA3	7	10	8	31	I/O	ST	
RA4	9	12	10	34	I/O	ST	
RA7	—	—	—	13	I/O	ST	
RA8	—	—	—	32	I/O	ST	
RA9	—	—	—	35	I/O	ST	
RA10	—	—	—	12	I/O	ST	
RB0	1	4	35	21	I/O	ST	PORTB is a bidirectional I/O port
RB1	2	5	36	22	I/O	ST	
RB2	3	6	1	23	I/O	ST	
RB3	4	7	2	24	I/O	ST	
RB4	8	11	9	33	I/O	ST	
RB5	11	14	15	41	I/O	ST	
RB6	12 ⁽²⁾	15 ⁽²⁾	16 ⁽²⁾	42 ⁽²⁾	I/O	ST	
RB7	13	16	17	43	I/O	ST	
RB8	14	17	18	44	I/O	ST	
RB9	15	18	19	1	I/O	ST	
RB10	18	21	24	8	I/O	ST	
RB11	19	22	25	9	I/O	ST	
RB12	20 ⁽²⁾	23 ⁽²⁾	26 ⁽²⁾	10 ⁽²⁾	I/O	ST	
RB13	21	24	27	11	I/O	ST	
RB14	22	25	28	14	I/O	ST	
RB15	23	26	29	15	I/O	ST	

Legend: CMOS = CMOS compatible input or output
ST = Schmitt Trigger input with CMOS levels
TTL = TTL input buffer

Analog = Analog input
O = Output
PPS = Peripheral Pin Select

P = Power
I = Input
— = N/A

Note 1: Pin numbers are provided for reference only. See the “Pin Diagrams” section for device pin availability.
2: Pin number for PIC32MX1XX devices only.
3: Pin number for PIC32MX2XX devices only.

PIC32MX1XX/2XX 28/36/44-PIN FAMILY

2.0 GUIDELINES FOR GETTING STARTED WITH 32-BIT MCUs

Note: This data sheet summarizes the features of the PIC32MX1XX/2XX 28/36/44-pin Family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to the documents listed in the *Documentation > Reference Manual* section of the Microchip PIC32 web site (www.microchip.com/pic32).

2.1 Basic Connection Requirements

Getting started with the PIC32MX1XX/2XX 28/36/44-pin Family of 32-bit Microcontrollers (MCUs) requires attention to a minimal set of device pin connections before proceeding with development. The following is a list of pin names, which must always be connected:

- All VDD and VSS pins (see 2.2 “Decoupling Capacitors”)
- All AVDD and AVSS pins, even if the ADC module is not used (see 2.2 “Decoupling Capacitors”)
- VCAP pin (see 2.3 “Capacitor on Internal Voltage Regulator (VCAP)”)
- MCLR pin (see 2.4 “Master Clear (MCLR) Pin”)
- PGECx/PGEDx pins, used for In-Circuit Serial Programming™ (ICSP™) and debugging purposes (see 2.5 “ICSP Pins”)
- OSC1 and OSC2 pins, when external oscillator source is used (see 2.7 “External Oscillator Pins”)

The following pins may be required:

- VREF+/VREF- pins – used when external voltage reference for the ADC module is implemented

Note: The AVDD and AVSS pins must be connected, regardless of ADC use and the ADC voltage reference source.

2.2 Decoupling Capacitors

The use of decoupling capacitors on power supply pins, such as VDD, VSS, AVDD and AVSS is required. See Figure 2-1.

Consider the following criteria when using decoupling capacitors:

- **Value and type of capacitor:** A value of 0.1 μF (100 nF), 10-20V is recommended. The capacitor should be a low Equivalent Series Resistance (low-ESR) capacitor and have resonance frequency in the range of 20 MHz and higher. It is further recommended that ceramic capacitors be used.
- **Placement on the printed circuit board:** The decoupling capacitors should be placed as close to the pins as possible. It is recommended that the capacitors be placed on the same side of the board as the device. If space is constricted, the capacitor can be placed on another layer on the PCB using a via; however, ensure that the trace length from the pin to the capacitor is within one-quarter inch (6 mm) in length.
- **Handling high frequency noise:** If the board is experiencing high frequency noise, upward of tens of MHz, add a second ceramic-type capacitor in parallel to the above described decoupling capacitor. The value of the second capacitor can be in the range of 0.01 μF to 0.001 μF . Place this second capacitor next to the primary decoupling capacitor. In high-speed circuit designs, consider implementing a decade pair of capacitances as close to the power and ground pins as possible. For example, 0.1 μF in parallel with 0.001 μF .
- **Maximizing performance:** On the board layout from the power supply circuit, run the power and return traces to the decoupling capacitors first, and then to the device pins. This ensures that the decoupling capacitors are first in the power chain. Equally important is to keep the trace length between the capacitor and the power pins to a minimum thereby reducing PCB track inductance.

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REGISTER 6-1: RCON: RESET CONTROL REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	U-0	U-0	U-0	U-0	U-0	U-0	R/W-0, HS	R/W-0
	—	—	—	—	—	—	CMR	VREGS
7:0	R/W-0, HS	R/W-0, HS	U-0	R/W-0, HS	R/W-0, HS	R/W-0, HS	R/W-1, HS	R/W-1, HS
	EXTR	SWR	—	WDTO	SLEEP	IDLE	BOR ⁽¹⁾	POR ⁽¹⁾

Legend:

R = Readable bit

-n = Value at POR

HS = Set by hardware

W = Writable bit

'1' = Bit is set

U = Unimplemented bit, read as '0'

'0' = Bit is cleared

x = Bit is unknown

bit 31-10 **Unimplemented:** Read as '0'

bit 9 **CMR:** Configuration Mismatch Reset Flag bit
 1 = Configuration mismatch Reset has occurred
 0 = Configuration mismatch Reset has not occurred

bit 8 **VREGS:** Voltage Regulator Standby Enable bit
 1 = Regulator is enabled and is on during Sleep mode
 0 = Regulator is disabled and is off during Sleep mode

bit 7 **EXTR:** External Reset ($\overline{\text{MCLR}}$) Pin Flag bit
 1 = Master Clear (pin) Reset has occurred
 0 = Master Clear (pin) Reset has not occurred

bit 6 **SWR:** Software Reset Flag bit
 1 = Software Reset was executed
 0 = Software Reset as not executed

bit 5 **Unimplemented:** Read as '0'

bit 4 **WDTO:** Watchdog Timer Time-out Flag bit
 1 = WDT Time-out has occurred
 0 = WDT Time-out has not occurred

bit 3 **SLEEP:** Wake From Sleep Flag bit
 1 = Device was in Sleep mode
 0 = Device was not in Sleep mode

bit 2 **IDLE:** Wake From Idle Flag bit
 1 = Device was in Idle mode
 0 = Device was not in Idle mode

bit 1 **BOR:** Brown-out Reset Flag bit⁽¹⁾
 1 = Brown-out Reset has occurred
 0 = Brown-out Reset has not occurred

bit 0 **POR:** Power-on Reset Flag bit⁽¹⁾
 1 = Power-on Reset has occurred
 0 = Power-on Reset has not occurred

Note 1: User software must clear this bit to view next detection.

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REGISTER 10-6: U1IR: USB INTERRUPT REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
7:0	R/WC-0, HS	R/WC-0, HS	R/WC-0, HS	R/WC-0, HS	R/WC-0, HS	R/WC-0, HS	R-0	R/WC-0, HS
	STALLIF	ATTACHIF ⁽¹⁾	RESUMEIF ⁽²⁾	IDLEIF	TRNIF ⁽³⁾	SOFIF	UERRIF ⁽⁴⁾	URSTIF ⁽⁵⁾
								DETACHIF ⁽⁶⁾

Legend: WC = Write '1' to clear HS = Hardware Settable bit
R = Readable bit W = Writable bit U = Unimplemented bit, read as '0'
-n = Value at POR '1' = Bit is set '0' = Bit is cleared x = Bit is unknown

bit 31-8 **Unimplemented:** Read as '0'

bit 7 **STALLIF:** STALL Handshake Interrupt bit

1 = In Host mode a STALL handshake was received during the handshake phase of the transaction
In Device mode a STALL handshake was transmitted during the handshake phase of the transaction
0 = STALL handshake has not been sent

bit 6 **ATTACHIF:** Peripheral Attach Interrupt bit⁽¹⁾

1 = Peripheral attachment was detected by the USB module
0 = Peripheral attachment was not detected

bit 5 **RESUMEIF:** Resume Interrupt bit⁽²⁾

1 = K-State is observed on the D+ or D- pin for 2.5 μ s
0 = K-State is not observed

bit 4 **IDLEIF:** Idle Detect Interrupt bit

1 = Idle condition detected (constant Idle state of 3 ms or more)
0 = No Idle condition detected

bit 3 **TRNIF:** Token Processing Complete Interrupt bit⁽³⁾

1 = Processing of current token is complete; a read of the U1STAT register will provide endpoint information
0 = Processing of current token not complete

bit 2 **SOFIF:** SOF Token Interrupt bit

1 = SOF token received by the peripheral or the SOF threshold reached by the host
0 = SOF token was not received nor threshold reached

bit 1 **UERRIF:** USB Error Condition Interrupt bit⁽⁴⁾

1 = Unmasked error condition has occurred
0 = Unmasked error condition has not occurred

bit 0 **URSTIF:** USB Reset Interrupt bit (Device mode)⁽⁵⁾

1 = Valid USB Reset has occurred
0 = No USB Reset has occurred

DETACHIF: USB Detach Interrupt bit (Host mode)⁽⁶⁾

1 = Peripheral detachment was detected by the USB module
0 = Peripheral detachment was not detected

Note 1: This bit is valid only if the HOSTEN bit is set (see Register 10-11), there is no activity on the USB for 2.5 μ s, and the current bus state is not SE0.

2: When not in Suspend mode, this interrupt should be disabled.

3: Clearing this bit will cause the STAT FIFO to advance.

4: Only error conditions enabled through the U1EIE register will set this bit.

5: Device mode.

6: Host mode.

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REGISTER 10-11: U1CON: USB CONTROL REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
7:0	R-x	R-x	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	JSTATE	SE0	PKTDIS ⁽⁴⁾ TOKBUSY ^(1,5)	USBRST	HOSTEN ⁽²⁾	RESUME ⁽³⁾	PPBRST	USBEN ⁽⁴⁾ SOFEN ⁽⁵⁾

Legend:

R = Readable bit

W = Writable bit

U = Unimplemented bit, read as '0'

-n = Value at POR

'1' = Bit is set

'0' = Bit is cleared

x = Bit is unknown

bit 31-8 **Unimplemented:** Read as '0'

bit 7 **JSTATE:** Live Differential Receiver JSTATE flag bit

1 = JSTATE was detected on the USB

0 = No JSTATE was detected

bit 6 **SE0:** Live Single-Ended Zero flag bit

1 = Single-Ended Zero was detected on the USB

0 = No Single-Ended Zero was detected

bit 5 **PKTDIS:** Packet Transfer Disable bit⁽⁴⁾

1 = Token and packet processing is disabled (set upon SETUP token received)

0 = Token and packet processing is enabled

TOKBUSY: Token Busy Indicator bit^(1,5)

1 = Token is being executed by the USB module

0 = No token is being executed

bit 4 **USBRST:** Module Reset bit⁽⁵⁾

1 = USB reset generated

0 = USB reset terminated

bit 3 **HOSTEN:** Host Mode Enable bit⁽²⁾

1 = USB host capability is enabled

0 = USB host capability is disabled

bit 2 **RESUME:** RESUME Signaling Enable bit⁽³⁾

1 = RESUME signaling is activated

0 = RESUME signaling is disabled

Note 1: Software is required to check this bit before issuing another token command to the U1TOK register (see Register 10-15).

2: All host control logic is reset any time that the value of this bit is toggled.

3: Software must set RESUME for 10 ms if the part is a function, or for 25 ms if the part is a host, and then clear it to enable remote wake-up. In Host mode, the USB module will append a Low-Speed EOP to the RESUME signaling when this bit is cleared.

4: Device mode.

5: Host mode.

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REGISTER 25-1: CTMUCON: CTMU CONTROL REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	R/W-0 EDG1MOD	R/W-0 EDG1POL	EDG1SEL<3:0>				R/W-0 EDG2STAT	R/W-0 EDG1STAT
23:16	R/W-0 EDG2MOD	R/W-0 EDG2POL	EDG2SEL<3:0>				U-0 —	U-0 —
15:8	R/W-0 ON	U-0 —	R/W-0 CTMUSIDL	R/W-0 TGEN ⁽¹⁾	R/W-0 EDGEN	R/W-0 EDGSEQEN	R/W-0 IDISSEN ⁽²⁾	R/W-0 CTTRIG
7:0	ITRIM<5:0>						IRNG<1:0>	

Legend:

R = Readable bit

W = Writable bit

U = Unimplemented bit, read as '0'

-n = Value at POR

'1' = Bit is set

'0' = Bit is cleared

x = Bit is unknown

bit 31 **EDG1MOD:** Edge1 Edge Sampling Select bit

1 = Input is edge-sensitive

0 = Input is level-sensitive

bit 30 **EDG1POL:** Edge 1 Polarity Select bit

1 = Edge1 programmed for a positive edge response

0 = Edge1 programmed for a negative edge response

bit 29-26 **EDG1SEL<3:0>:** Edge 1 Source Select bits

1111 = C3OUT pin is selected

1110 = C2OUT pin is selected

1101 = C1OUT pin is selected

1100 = IC3 Capture Event is selected

1011 = IC2 Capture Event is selected

1010 = IC1 Capture Event is selected

1001 = CTED8 pin is selected

1000 = CTED7 pin is selected

0111 = CTED6 pin is selected

0110 = CTED5 pin is selected

0101 = CTED4 pin is selected

0100 = CTED3 pin is selected

0011 = CTED1 pin is selected

0010 = CTED2 pin is selected

0001 = OC1 Compare Event is selected

0000 = Timer1 Event is selected

bit 25 **EDG2STAT:** Edge2 Status bit

Indicates the status of Edge2 and can be written to control edge source

1 = Edge2 has occurred

0 = Edge2 has not occurred

Note 1: When this bit is set for Pulse Delay Generation, the EDG2SEL<3:0> bits must be set to '1110' to select C2OUT.

2: The ADC module Sample and Hold capacitor is not automatically discharged between sample/conversion cycles. Software using the ADC as part of a capacitive measurement, must discharge the ADC capacitor before conducting the measurement. The IDISSEN bit, when set to '1', performs this function. The ADC module must be sampling while the IDISSEN bit is active to connect the discharge sink to the capacitor array.

3: Refer to the CTMU Current Source Specifications (Table 30-41) in **Section 30.0 "Electrical Characteristics"** for current values.

4: This bit setting is not available for the CTMU temperature diode.

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REGISTER 27-1: DEVCFG0: DEVICE CONFIGURATION WORD 0 (CONTINUED)

bit 18-10 **PWP<8:0>**: Program Flash Write-Protect bits⁽³⁾

Prevents selected program Flash memory pages from being modified during code execution.

11111111 = Disabled

11111110 = Memory below 0x0400 address is write-protected

11111101 = Memory below 0x0800 address is write-protected

11111100 = Memory below 0x0C00 address is write-protected

11111011 = Memory below 0x1000 (4K) address is write-protected

11111010 = Memory below 0x1400 address is write-protected

11111001 = Memory below 0x1800 address is write-protected

11111000 = Memory below 0x1C00 address is write-protected

11110111 = Memory below 0x2000 (8K) address is write-protected

11110110 = Memory below 0x2400 address is write-protected

11110101 = Memory below 0x2800 address is write-protected

11110100 = Memory below 0x2C00 address is write-protected

11110011 = Memory below 0x3000 address is write-protected

11110010 = Memory below 0x3400 address is write-protected

11110001 = Memory below 0x3800 address is write-protected

11110000 = Memory below 0x3C00 address is write-protected

11101111 = Memory below 0x4000 (16K) address is write-protected

.

.

.

11011111 = Memory below 0x10000 (64K) address is write-protected

.

.

.

10111111 = Memory below 0x20000 (128K) address is write-protected

.

.

.

01111111 = Memory below 0x40000 (256K) address is write-protected

.

.

.

00000000 = All possible memory is write-protected

bit 9-5 **Reserved**: Write '1'

bit 4-3 **ICESEL<1:0>**: In-Circuit Emulator/Debugger Communication Channel Select bits⁽²⁾

11 = PGEC1/PGED1 pair is used

10 = PGEC2/PGED2 pair is used

01 = PGEC3/PGED3 pair is used

00 = PGEC4/PGED4 pair is used⁽²⁾

bit 2 **JTAGEN**: JTAG Enable bit⁽¹⁾

1 = JTAG is enabled

0 = JTAG is disabled

bit 1-0 **DEBUG<1:0>**: Background Debugger Enable bits (forced to '11' if code-protect is enabled)

1x = Debugger is disabled

0x = Debugger is enabled

Note 1: This bit sets the value for the JTAGEN bit in the CFGCON register.

2: The PGEC4/PGED4 pin pair is not available on all devices. Refer to the “Pin Diagrams” section for availability.

3: The PWP<8:7> bits are only available on devices with 256 KB Flash.

PIC32MX1XX/2XX 28/36/44-PIN FAMILY

REGISTER 27-2: DEVCFG1: DEVICE CONFIGURATION WORD 1

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	r-1	r-1	r-1	r-1	r-1	r-1	R/P	R/P
	—	—	—	—	—	—	FWDTWINSZ<1:0>	
23:16	R/P	R/P	r-1	R/P	R/P	R/P	R/P	R/P
	FWDTEN	WINDIS	—	WDTPS<4:0>				
15:8	R/P	R/P	R/P	R/P	r-1	R/P	R/P	R/P
	FCKSM<1:0>		FPBDIV<1:0>		—	OSCIOFNC	POSCMOD<1:0>	
7:0	R/P	r-1	R/P	r-1	r-1	R/P	R/P	R/P
	IESO	—	FSOSCEN	—	—	FNOSC<2:0>		

Legend:

R = Readable bit

-n = Value at POR

r = Reserved bit

W = Writable bit

‘1’ = Bit is set

P = Programmable bit

U = Unimplemented bit, read as ‘0’

‘0’ = Bit is cleared

x = Bit is unknown

bit 31-26 **Reserved:** Write ‘1’

bit 25-24 **FWDTWINSZ<1:0>**: Watchdog Timer Window Size bits

11 = Window size is 25%

10 = Window size is 37.5%

01 = Window size is 50%

00 = Window size is 75%

bit 23 **FWDTEN**: Watchdog Timer Enable bit

1 = Watchdog Timer is enabled and cannot be disabled by software

0 = Watchdog Timer is not enabled; it can be enabled in software

bit 22 **WINDIS**: Watchdog Timer Window Enable bit

1 = Watchdog Timer is in non-Window mode

0 = Watchdog Timer is in Window mode

bit 21 **Reserved:** Write ‘1’

bit 20-16 **WDTPS<4:0>**: Watchdog Timer Postscale Select bits

10100 = 1:1048576

10011 = 1:524288

10010 = 1:262144

10001 = 1:131072

10000 = 1:65536

01111 = 1:32768

01110 = 1:16384

01101 = 1:8192

01100 = 1:4096

01011 = 1:2048

01010 = 1:1024

01001 = 1:512

01000 = 1:256

00111 = 1:128

00110 = 1:64

00101 = 1:32

00100 = 1:16

00011 = 1:8

00010 = 1:4

00001 = 1:2

00000 = 1:1

All other combinations not shown result in operation = 10100

Note 1: Do not disable the Posc (POSCMOD = 11) when using this oscillator source.

PIC32MX1XX/2XX 28/36/44-PIN FAMILY

REGISTER 27-3: DEVCFG2: DEVICE CONFIGURATION WORD 2

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	r-1	r-1	r-1	r-1	r-1	r-1	r-1	r-1
	—	—	—	—	—	—	—	—
23:16	r-1	r-1	r-1	r-1	r-1	R/P	R/P	R/P
	—	—	—	—	—	FPLLODIV<2:0>		
15:8	R/P	r-1	r-1	r-1	r-1	R/P	R/P	R/P
	UPLLEN ⁽¹⁾	—	—	—	—	UPLLDIV<2:0> ⁽¹⁾		
7:0	r-1	R/P-1	R/P	R/P-1	r-1	R/P	R/P	R/P
	—	FPLLMUL<2:0>			—	FPLLDIV<2:0>		

Legend:	r = Reserved bit	P = Programmable bit
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared x = Bit is unknown

bit 31-19 **Reserved:** Write '1'

bit 18-16 **FPLLODIV<2:0>:** Default PLL Output Divisor bits

111 = PLL output divided by 256
110 = PLL output divided by 64
101 = PLL output divided by 32
100 = PLL output divided by 16
011 = PLL output divided by 8
010 = PLL output divided by 4
001 = PLL output divided by 2
000 = PLL output divided by 1

bit 15 **UPLLEN:** USB PLL Enable bit⁽¹⁾
1 = Disable and bypass USB PLL
0 = Enable USB PLL

bit 14-11 **Reserved:** Write '1'

bit 10-8 **UPLLDIV<2:0>:** USB PLL Input Divider bits⁽¹⁾

111 = 12x divider
110 = 10x divider
101 = 6x divider
100 = 5x divider
011 = 4x divider
010 = 3x divider
010 = 3x divider
001 = 2x divider
000 = 1x divider

bit 7 **Reserved:** Write '1'

bit 6-4 **FPLLMUL<2:0>:** PLL Multiplier bits

111 = 24x multiplier
110 = 21x multiplier
101 = 20x multiplier
100 = 19x multiplier
011 = 18x multiplier
010 = 17x multiplier
001 = 16x multiplier
000 = 15x multiplier

bit 3 **Reserved:** Write '1'

Note 1: This bit is only available on PIC32MX2XX devices.

PIC32MX1XX/2XX 28/36/44-PIN FAMILY

REGISTER 27-5: CFGCON: CONFIGURATION CONTROL REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	U-0	U-0	R/W-0	R/W-0	U-0	U-0	U-0	U-0
	—	—	IOLOCK ⁽¹⁾	PMDLOCK ⁽¹⁾	—	—	—	—
7:0	U-0	U-0	U-0	U-0	R/W-1	U-0	U-1	R/W-1
	—	—	—	—	JTAGEN	—	—	TDOEN

Legend:

R = Readable bit

W = Writable bit

U = Unimplemented bit, read as '0'

-n = Value at POR

'1' = Bit is set

'0' = Bit is cleared

x = Bit is unknown

bit 31-14 **Unimplemented:** Read as '0'

bit 13 **IOLOCK:** Peripheral Pin Select Lock bit⁽¹⁾

1 = Peripheral Pin Select is locked. Writes to PPS registers is not allowed.

0 = Peripheral Pin Select is not locked. Writes to PPS registers is allowed.

bit 12 **PMDLOCK:** Peripheral Module Disable bit⁽¹⁾

1 = Peripheral module is locked. Writes to PMD registers is not allowed.

0 = Peripheral module is not locked. Writes to PMD registers is allowed.

bit 11-4 **Unimplemented:** Read as '0'

bit 3 **JTAGEN:** JTAG Port Enable bit

1 = Enable the JTAG port

0 = Disable the JTAG port

bit 2-1 **Unimplemented:** Read as '1'

bit 0 **TDOEN:** TDO Enable for 2-Wire JTAG bit

1 = 2-wire JTAG protocol uses TDO

0 = 2-wire JTAG protocol does not use TDO

Note 1: To change this bit, the unlock sequence must be performed. Refer to **Section 6. "Oscillator"** (DS60001112) in the *"PIC32 Family Reference Manual"* for details.

PIC32MX1XX/2XX 28/36/44-PIN FAMILY

29.2 MPLAB XC Compilers

The MPLAB XC Compilers are complete ANSI C compilers for all of Microchip's 8, 16, and 32-bit MCU and DSC devices. These compilers provide powerful integration capabilities, superior code optimization and ease of use. MPLAB XC Compilers run on Windows, Linux or MAC OS X.

For easy source level debugging, the compilers provide debug information that is optimized to the MPLAB X IDE.

The free MPLAB XC Compiler editions support all devices and commands, with no time or memory restrictions, and offer sufficient code optimization for most applications.

MPLAB XC Compilers include an assembler, linker and utilities. The assembler generates relocatable object files that can then be archived or linked with other relocatable object files and archives to create an executable file. MPLAB XC Compiler uses the assembler to produce its object file. Notable features of the assembler include:

- Support for the entire device instruction set
- Support for fixed-point and floating-point data
- Command-line interface
- Rich directive set
- Flexible macro language
- MPLAB X IDE compatibility

29.3 MPASM Assembler

The MPASM Assembler is a full-featured, universal macro assembler for PIC10/12/16/18 MCUs.

The MPASM Assembler generates relocatable object files for the MPLINK Object Linker, Intel® standard HEX files, MAP files to detail memory usage and symbol reference, absolute LST files that contain source lines and generated machine code, and COFF files for debugging.

The MPASM Assembler features include:

- Integration into MPLAB X IDE projects
- User-defined macros to streamline assembly code
- Conditional assembly for multipurpose source files
- Directives that allow complete control over the assembly process

29.4 MPLINK Object Linker/ MPLIB Object Librarian

The MPLINK Object Linker combines relocatable objects created by the MPASM Assembler. It can link relocatable objects from precompiled libraries, using directives from a linker script.

The MPLIB Object Librarian manages the creation and modification of library files of precompiled code. When a routine from a library is called from a source file, only the modules that contain that routine will be linked in with the application. This allows large libraries to be used efficiently in many different applications.

The object linker/librarian features include:

- Efficient linking of single libraries instead of many smaller files
- Enhanced code maintainability by grouping related modules together
- Flexible creation of libraries with easy module listing, replacement, deletion and extraction

29.5 MPLAB Assembler, Linker and Librarian for Various Device Families

MPLAB Assembler produces relocatable machine code from symbolic assembly language for PIC24, PIC32 and dsPIC DSC devices. MPLAB XC Compiler uses the assembler to produce its object file. The assembler generates relocatable object files that can then be archived or linked with other relocatable object files and archives to create an executable file. Notable features of the assembler include:

- Support for the entire device instruction set
- Support for fixed-point and floating-point data
- Command-line interface
- Rich directive set
- Flexible macro language
- MPLAB X IDE compatibility

PIC32MX1XX/2XX 28/36/44-PIN FAMILY

TABLE 30-4: DC TEMPERATURE AND VOLTAGE SPECIFICATIONS

DC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature $-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$ for Industrial $-40^{\circ}\text{C} \leq T_A \leq +105^{\circ}\text{C}$ for V-temp				
Param. No.	Symbol	Characteristics	Min.	Typ.	Max.	Units	Conditions
Operating Voltage							
DC10	VDD	Supply Voltage (Note 2)	2.3	—	3.6	V	—
DC12	VDR	RAM Data Retention Voltage (Note 1)	1.75	—	—	V	—
DC16	VPOR	VDD Start Voltage to Ensure Internal Power-on Reset Signal	1.75	—	2.1	V	—
DC17	SVDD	VDD Rise Rate to Ensure Internal Power-on Reset Signal	0.00005	—	0.115	V/ μs	—

Note 1: This is the limit to which VDD can be lowered without losing RAM data.

- 2:** Overall functional device operation at $V_{BORMIN} < VDD < VDDMIN$ is tested, but not characterized. All device Analog modules, such as ADC, etc., will function, but with degraded performance below VDDMIN. Refer to parameter BO10 in Table 30-11 for BOR values.

PIC32MX1XX/2XX 28/36/44-PIN FAMILY

TABLE 30-7: DC CHARACTERISTICS: POWER-DOWN CURRENT (IPD)

DC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp		
Param. No.	Typical ⁽²⁾	Max.	Units	Conditions	
Power-Down Current (IPD) (Notes 1, 5)					
DC40k	44	70	μA	-40°C	Base Power-Down Current
DC40l	44	70	μA	+25°C	
DC40n	168	259	μA	+85°C	
DC40m	335	536	μA	+105°C	
Module Differential Current					
DC41e	5	20	μA	3.6V	Watchdog Timer Current: ΔIWDT (Note 3)
DC42e	23	50	μA	3.6V	RTCC + Timer1 w/32 kHz Crystal: ΔIRTCC (Note 3)
DC43d	1000	1100	μA	3.6V	ADC: ΔIADC (Notes 3,4)

- Note 1:** The test conditions for IPD current measurements are as follows:
- Oscillator mode is EC (for 8 MHz and below) and EC+PLL (for above 8 MHz) with OSC1 driven by external square wave from rail-to-rail, (OSC1 input clock input over/undershoot < 100 mV required)
 - OSC2/CLKO is configured as an I/O input pin
 - USB PLL oscillator is disabled if the USB module is implemented, PBCLK divisor = 1:8
 - CPU is in Sleep mode, and SRAM data memory Wait states = 1
 - No peripheral modules are operating, (ON bit = 0), but the associated PMD bit is set
 - WDT, Clock Switching, Fail-Safe Clock Monitor, and Secondary Oscillator are disabled
 - All I/O pins are configured as inputs and pulled to V_{SS}
 - $\overline{\text{MCLR}} = \text{V}_{\text{DD}}$
 - RTCC and JTAG are disabled
- 2:** Data in the “Typical” column is at 3.3V, 25°C unless otherwise stated. Parameters are for design guidance only and are not tested.
- 3:** The Δ current is the additional current consumed when the module is enabled. This current should be added to the base IPD current.
- 4:** Test conditions for ADC module differential current are as follows: Internal ADC RC oscillator enabled.
- 5:** IPD electrical characteristics for devices with 256 KB Flash are only provided as Preliminary information.

PIC32MX1XX/2XX 28/36/44-PIN FAMILY

TABLE 30-14: COMPARATOR VOLTAGE REFERENCE SPECIFICATIONS

DC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature $-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$ for Industrial $-40^{\circ}\text{C} \leq T_A \leq +105^{\circ}\text{C}$ for V-temp				
Param. No.	Symbol	Characteristics	Min.	Typ.	Max.	Units	Comments
D312	TSET	Internal 4-bit DAC Comparator Reference Settling time	—	—	10	μs	See Note 1
D313	DACREFH	CVREF Input Voltage Reference Range	AVSS	—	AVDD	V	CVRSRC with CVRSS = 0
			VREF-	—	VREF+	V	CVRSRC with CVRSS = 1
D314	DVREF	CVREF Programmable Output Range	0	—	$0.625 \times \text{DACREFH}$	V	0 to $0.625 \times \text{DACREFH}$ with $\text{DACREFH}/24$ step size
			$0.25 \times \text{DACREFH}$	—	$0.719 \times \text{DACREFH}$	V	$0.25 \times \text{DACREFH}$ to $0.719 \times \text{DACREFH}$ with $\text{DACREFH}/32$ step size
D315	DACRES	Resolution	—	—	$\text{DACREFH}/24$	—	$\text{CVRCON} < \text{CVRR} > = 1$
			—	—	$\text{DACREFH}/32$	—	$\text{CVRCON} < \text{CVRR} > = 0$
D316	DACACC	Absolute Accuracy ⁽²⁾	—	—	1/4	LSB	$\text{DACREFH}/24$, $\text{CVRCON} < \text{CVRR} > = 1$
			—	—	1/2	LSB	$\text{DACREFH}/32$, $\text{CVRCON} < \text{CVRR} > = 0$

Note 1: Settling time was measured while $\text{CVRR} = 1$ and $\text{CVR} < 3:0 >$ transitions from '0000' to '1111'. This parameter is characterized, but is not tested in manufacturing.

2: These parameters are characterized but not tested.

TABLE 30-15: INTERNAL VOLTAGE REGULATOR SPECIFICATIONS

DC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature $-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$ for Industrial $-40^{\circ}\text{C} \leq T_A \leq +105^{\circ}\text{C}$ for V-temp				
Param. No.	Symbol	Characteristics	Min.	Typical	Max.	Units	Comments
D321	CEFC	External Filter Capacitor Value	8	10	—	μF	Capacitor must be low series resistance (1 ohm). Typical voltage on the VCAP pin is 1.8V.

PIC32MX1XX/2XX 28/36/44-PIN FAMILY

TABLE 30-17: EXTERNAL CLOCK TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp				
Param. No.	Symbol	Characteristics	Min.	Typical ⁽¹⁾	Max.	Units	Conditions
OS10	Fosc	External CLKI Frequency (External clocks allowed only in EC and ECPLL modes)	DC 4	— —	40 40	MHz MHz	EC (Note 4) ECPLL (Note 3)
OS11		Oscillator Crystal Frequency	3	—	10	MHz	XT (Note 4)
OS12			4	—	10	MHz	XTPLL (Notes 3,4)
OS13			10	—	25	MHz	HS (Note 5)
OS14			10	—	25	MHz	HSPLL (Notes 3,4)
OS15			32	32.768	100	kHz	Sosc (Note 4)
OS20	Tosc	Tosc = 1/Fosc = Tcy (Note 2)	—	—	—	—	See parameter OS10 for Fosc value
OS30	TosL, TosH	External Clock In (OSC1) High or Low Time	0.45 x Tosc	—	—	ns	EC (Note 4)
OS31	TosR, TosF	External Clock In (OSC1) Rise or Fall Time	—	—	0.05 x Tosc	ns	EC (Note 4)
OS40	TOST	Oscillator Start-up Timer Period (Only applies to HS, HSPLL, XT, XTPLL and Sosc Clock Oscillator modes)	—	1024	—	Tosc	(Note 4)
OS41	TfSCM	Primary Clock Fail Safe Time-out Period	—	2	—	ms	(Note 4)
OS42	GM	External Oscillator Transconductance (Primary Oscillator only)	—	12	—	mA/V	VDD = 3.3V, TA = +25°C (Note 4)

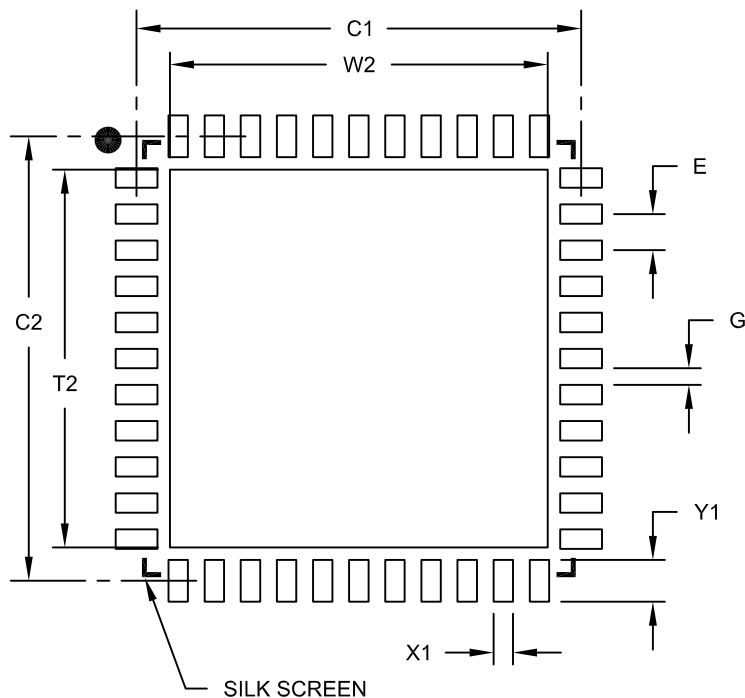
Note 1: Data in “Typical” column is at 3.3V, 25°C unless otherwise stated. Parameters are characterized but are not tested.

- 2:** Instruction cycle period (Tcy) equals the input oscillator time base period. All specified values are based on characterization data for that particular oscillator type under standard operating conditions with the device executing code. Exceeding these specified limits may result in an unstable oscillator operation and/or higher than expected current consumption. All devices are tested to operate at “min.” values with an external clock applied to the OSC1/CLKI pin.
- 3:** PLL input requirements: 4 MHz ≤ F_{PLLIN} ≤ 5 MHz (use PLL prescaler to reduce Fosc). This parameter is characterized, but tested at 10 MHz only at manufacturing.
- 4:** This parameter is characterized, but not tested in manufacturing.

PIC32MX1XX/2XX 28/36/44-PIN FAMILY

44-Lead Plastic Quad Flat, No Lead Package (ML) – 8x8 mm Body [QFN]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E		0.65 BSC	
Optional Center Pad Width	W2			6.80
Optional Center Pad Length	T2			6.80
Contact Pad Spacing	C1		8.00	
Contact Pad Spacing	C2		8.00	
Contact Pad Width (X44)	X1			0.35
Contact Pad Length (X44)	Y1			0.80
Distance Between Pads	G	0.25		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2103A

PIC32MX1XX/2XX 28/36/44-PIN FAMILY

TABLE A-1: MAJOR SECTION UPDATES (CONTINUED)

Section	Update Description
4.0 “Memory Organization”	Added Memory Maps for the new devices (see Figure 4-3 and Figure 4-4). Removed the BMXCHEDMA bit from the Bus Matrix Register map (see Table 4-1). Added the REFOTRIM register, added the DIVSWEN bit to the REFOCON registers, added Note 4 to the ULOCK and SOSSEN bits and added the PBDIVRDY bit in the OSCCON register in the in the System Control Register map (see Table 4-16). Removed the ALTI2C1 and ALTI2C2 bits from the DEVCFG3 register and added Note 1 to the UPLEN and UPLLIDIV<2:0> bits of the DEVCFG2 register in the Device Configuration Word Summary (see Table 4-17). Updated Note 1 in the Device and Revision ID Summary (see Table 4-18). Added Note 2 to the PORTA Register map (see Table 4-19). Added the ANSB6 and ANSB12 bits to the ANSELB register in the PORTB Register map (see Table 4-20). Added Notes 2 and 3 to the PORTC Register map (see Table 4-21). Updated all register names in the Peripheral Pin Select Register map (see Table 4-23). Added values in support of new devices (16 KB RAM and 32 KB RAM) in the Data RAM Size register (see Register 4-5). Added values in support of new devices (64 KB Flash and 128 KB Flash) in the Data RAM Size register (see Register 4-5).
8.0 “Oscillator Configuration”	Added Note 5 to the PIC32MX1XX/2XX Family Clock Diagram (see Figure 8-1). Added the PBDIVRDY bit and Note 2 to the Oscillator Control register (see Register 8-1). Added the DIVSWEN bit and Note 3 to the Reference Oscillator Control register (see Register 8-3). Added the REFOTRIM register (see Register 8-4).
21.0 “10-bit Analog-to-Digital Converter (ADC)”	Updated the ADC1 Module Block Diagram (see Figure 21-1). Updated the Notes in the ADC Input Select register (see Register 21-4).
24.0 “Charge Time Measurement Unit (CTMU)”	Updated the CTMU Block Diagram (see Figure 24-1). Added Note 3 to the CTMU Control register (see Register 24-1)
26.0 “Special Features”	Added Note 1 and the PGEC4/PGED4 pin pair to the ICESSEL<1:0> bits in DEVCFG0: Device Configuration Word 0 (see Register 26-1). Removed the ALTI2C1 and ALTI2C2 bits from the Device Configuration Word 3 register (see Register 26-4). Removed 26.3.3 “Power-up Requirements”. Added Note 3 to the Connections for the On-Chip Regulator diagram (see Figure 26-2). Updated the Block Diagram of Programming, Debugging and Trace Ports diagram (see Figure 26-3).